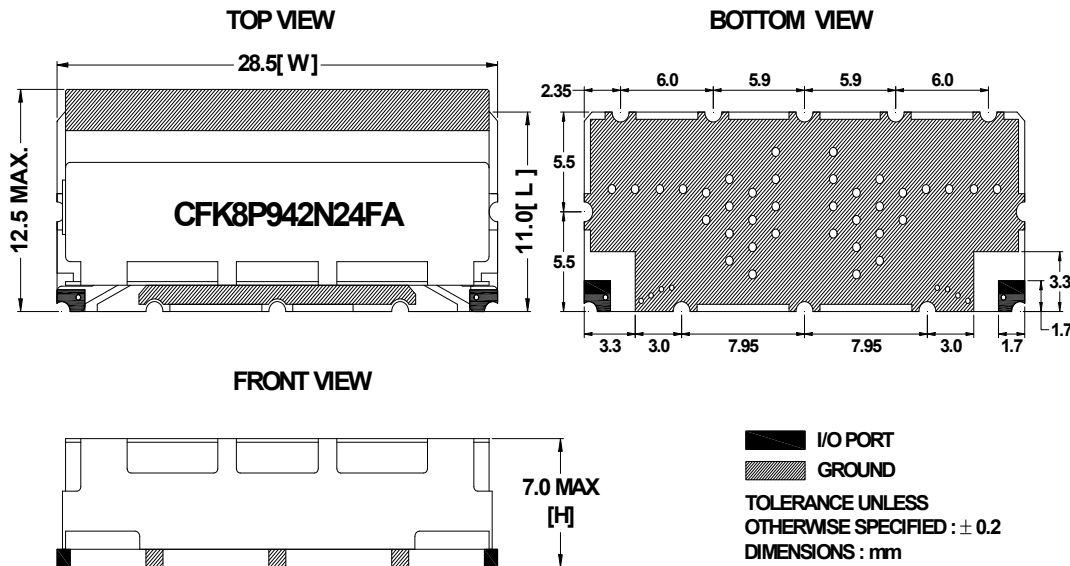


Electrical Specification

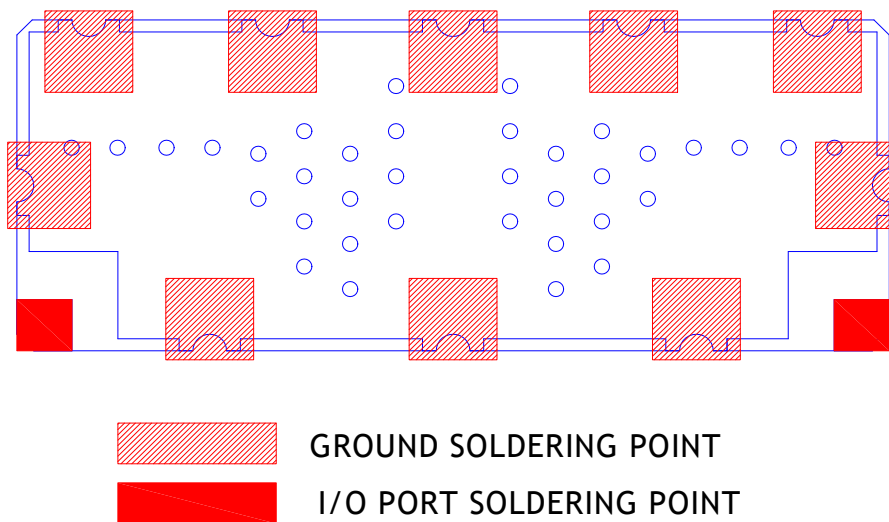
ITEMS	SPEC	UNIT
Center Frequency [fo]	942.0	MHz
Bandwidth [BW]	$fo \pm 12.0$ [930.0 ~ 954.0]	MHz
Insertion Loss in BW	8.0	dB max
Ripple in BW	3.0	dB max
Return Loss in BW	10.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	3.0 dBc min. @ $fo \pm 13.0$ [929.0 & 955.0]	MHz
	20.0 dBc min. @ $fo \pm 17.0$ [925.0 & 959.0]	MHz
	60.0 dBc min. @ $fo \pm$ [885.0 ~ 909.0]	MHz
	dB min @ $fo \pm$ [~]	MHz
Group Delay Variation		ns max
Input Power	2.0	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

Mechanical Specification

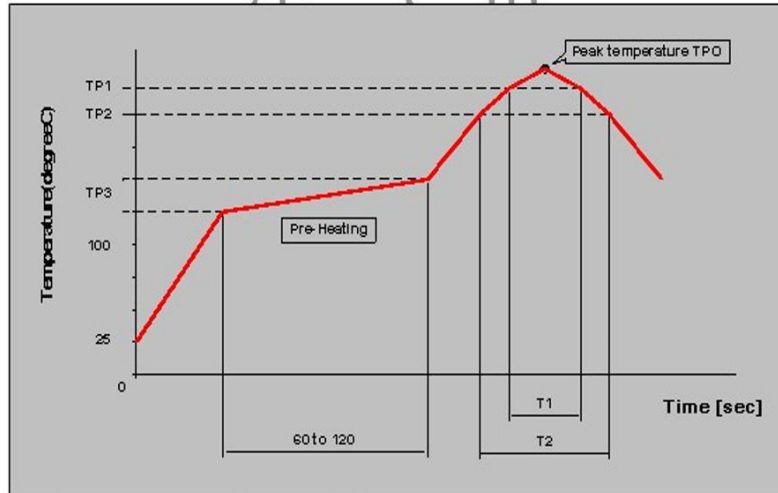


 Plot Data

 Recommended PC Board Pattern



 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180